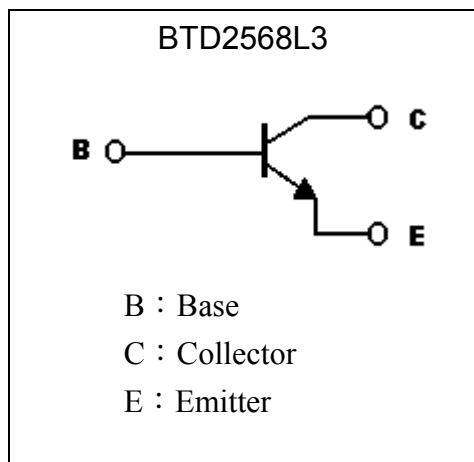
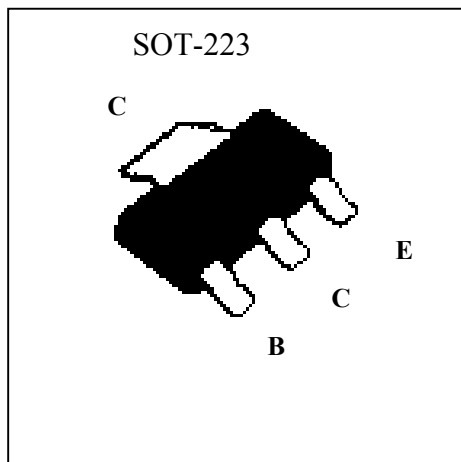


High Voltage NPN Epitaxial Planar Transistor

BTD2568L3

Features

- High V_{CEO} , 400V minimum

Symbol

Outline

Absolute Maximum Ratings ($T_a=25^{\circ}\text{C}$)

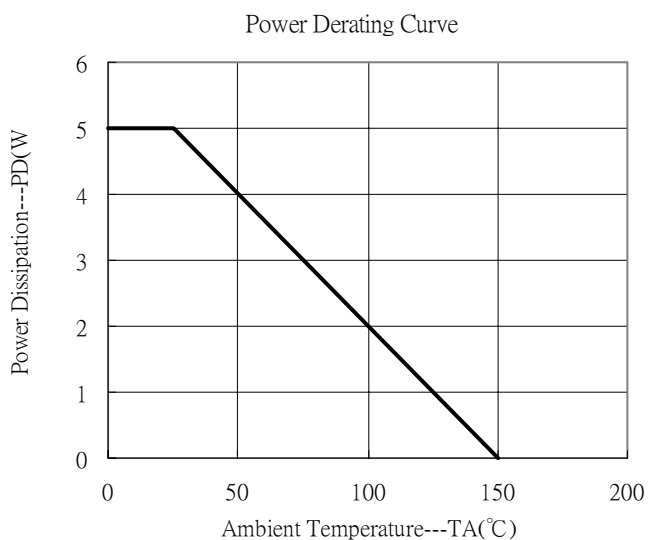
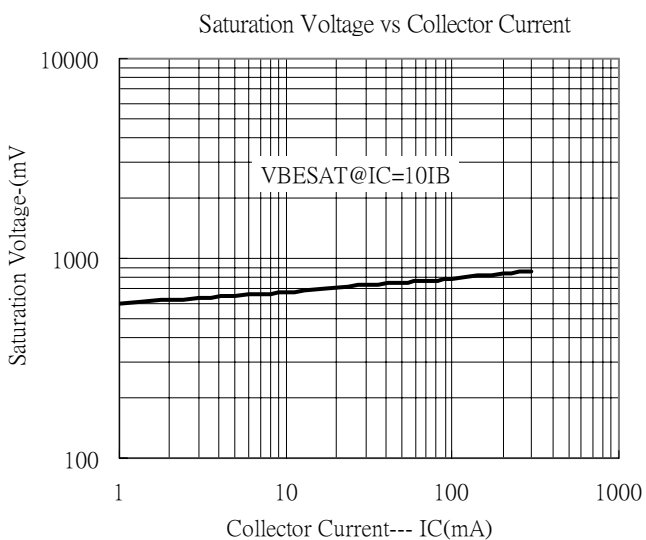
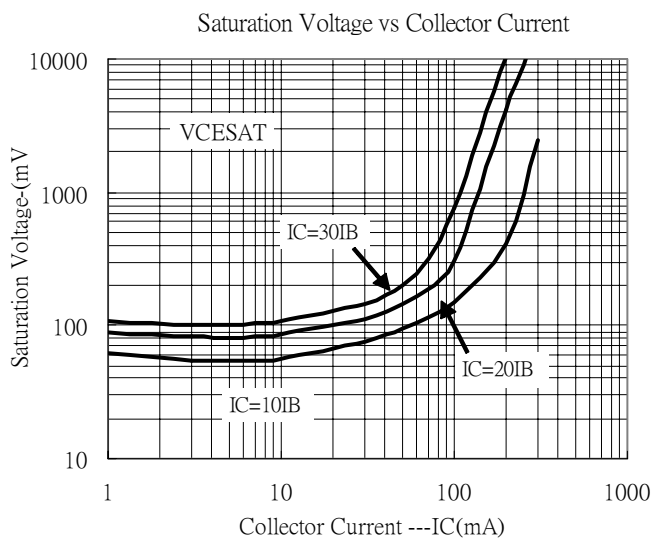
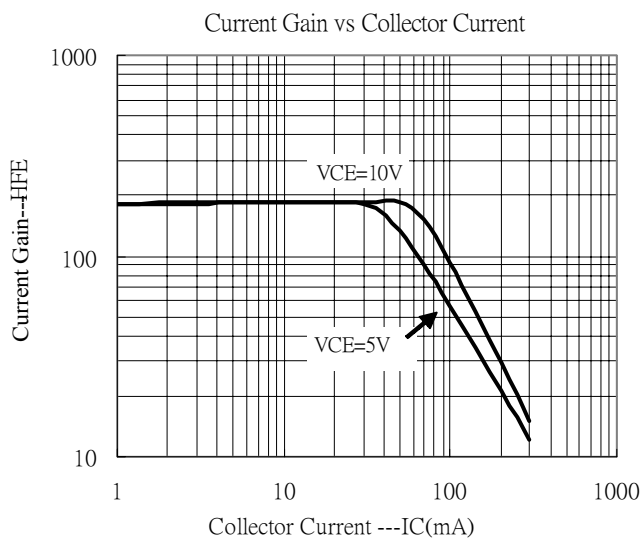
Parameter	Symbol	Limits	Unit
Collector-Base Voltage	V_{CBO}	400	V
Collector-Emitter Voltage	V_{CEO}	400	V
Emitter-Base Voltage	V_{EBO}	6	V
Collector Current(DC)	I_C	300	mA
Collector Current(Pulse)	I_{CP}	1	A
Base Current	I_B	200	mA
Power Dissipation @ $T_C=25^{\circ}\text{C}$	P_d	5	W
Junction Temperature	T_j	150	$^{\circ}\text{C}$
Storage Temperature	T_{stg}	-55~+150	$^{\circ}\text{C}$

**Characteristics (Ta=25°C)**

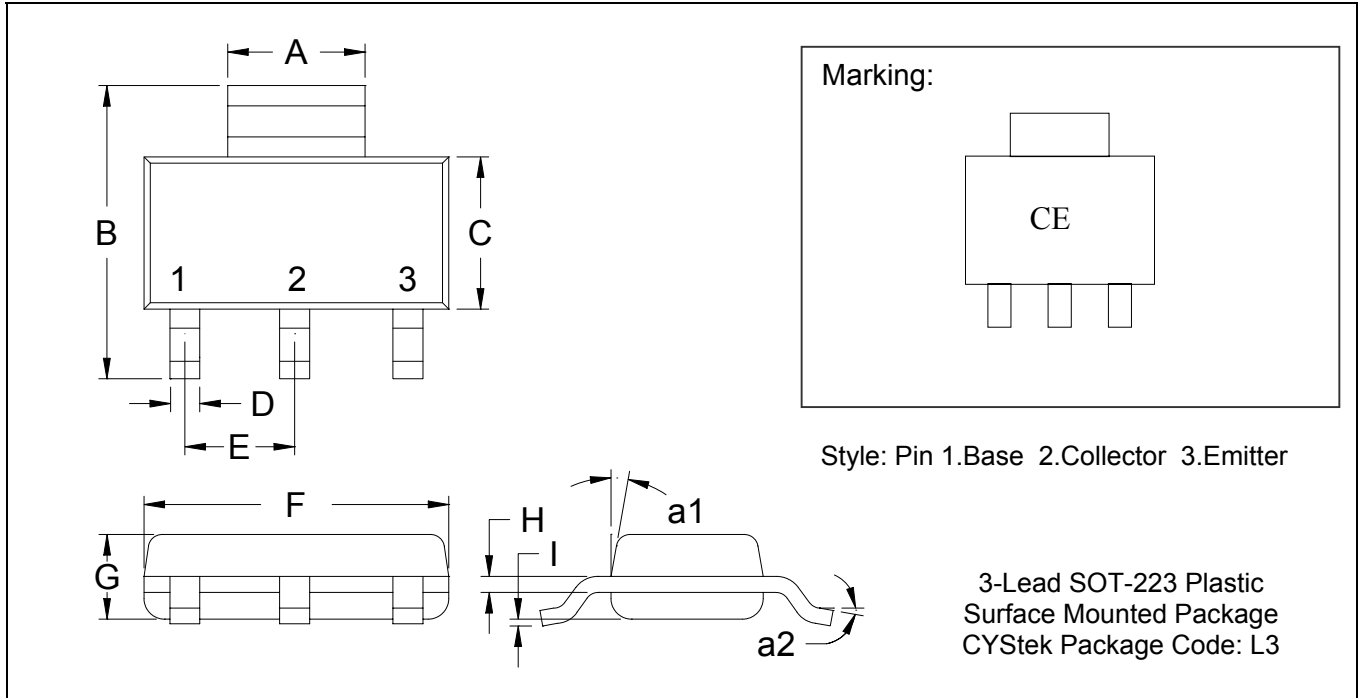
Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BV _{CB0}	400	-	-	V	I _C =100μA
BV _{CEO}	400	-	-	V	I _C =1mA
BV _{EBO}	6	-	-	V	I _E =10μA
I _{CB0}	-	-	100	nA	V _{CB} =400V
I _{CES}	-	-	100	nA	V _{CE} =360V
I _{EBO}	-	-	100	nA	V _{EB} =5V
*V _{CE(sat)1}	-	-	0.2	V	I _C =20mA, I _B =2mA
*V _{CE(sat)2}	-	-	0.4	V	I _C =50mA, I _B =5mA
*V _{BE(sat)1}	-	-	0.8	V	I _C =10mA, I _B =1mA
*V _{BE(sat)2}	-	-	0.9	V	I _C =50mA, I _B =5mA
*V _{BE(on)}	-	-	0.9	V	V _{CE} =10V, I _C =50mA
h _{FE1}	50	-	-	-	V _{CE} =10V, I _C =1mA
h _{FE2}	100	-	250	-	V _{CE} =10V, I _C =10mA
*h _{FE3}	100	-	250	-	V _{CE} =10V, I _C =50mA
*h _{FE4}	40	-	-	-	V _{CE} =10V, I _C =100mA
f _T	50	-	-	MHz	V _{CE} =10V, I _C =10mA
Cob	-	3.5	-	pF	V _{CB} =20V, I _E =0A, f=1MHz

*Pulse Test: Pulse Width ≤380μs, Duty Cycle ≤2%

Characteristic Curves



SOT-223 Dimension



*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1142	0.1220	2.90	3.10	G	0.0551	0.0709	1.40	1.80
B	0.2638	0.2874	6.70	7.30	H	0.0098	0.0138	0.25	0.35
C	0.1299	0.1457	3.30	3.70	I	0.0008	0.0039	0.02	0.10
D	0.0236	0.0315	0.60	0.80	a1	*13°	-	*13°	-
E	*0.0906	-	*2.30	-	a2	0°	10°	0°	10°
F	0.2480	0.2638	6.30	6.70					

- Notes: 1.Controlling dimension: millimeters.
 2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material:

- Lead: 42 Alloy; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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